ATTY DKT. NO.:
U.S. SERIAL NO.:
FILED:
APPLICANT:
TITLE:
SUBSTRATES
INVENTOR:

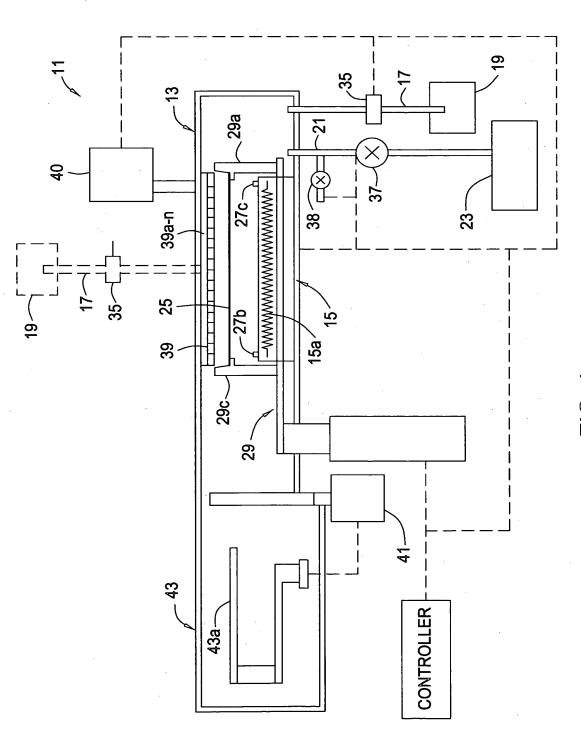
AMAT/1717.C3/CPES/DT/PJS 10/701,387 CONF. NO.: UNKNOWN NOVEMBER 4, 2003 APPLIED MATERIALS METHOD AND APPARATUS FOR HEATING AND COOLING

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TITLE: SUBSTRATES INVENTOR: MORAD, ET AL.

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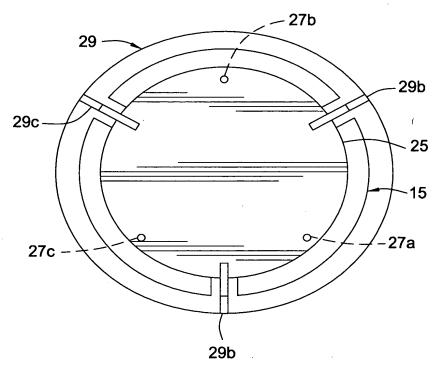


FIG. 2

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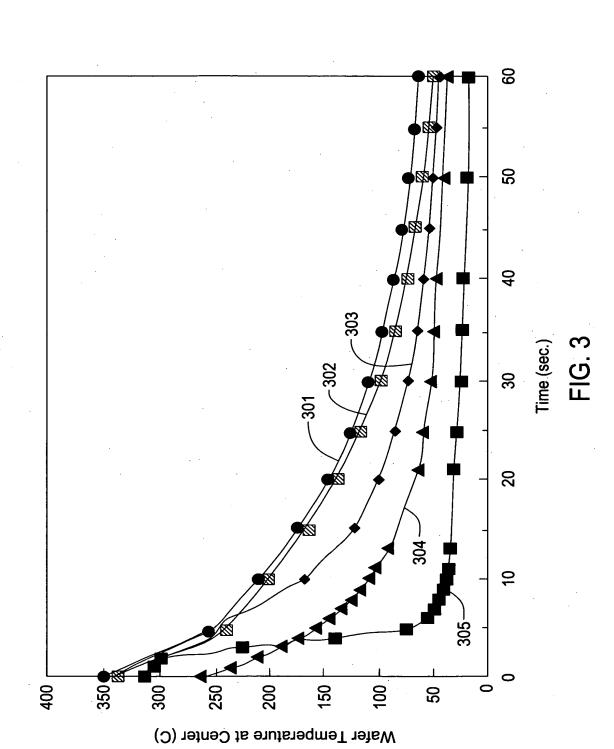
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CONF. NO.: UNKNOWN





APPLICANT: TITLE: SUBSTRATES INVENTOR:

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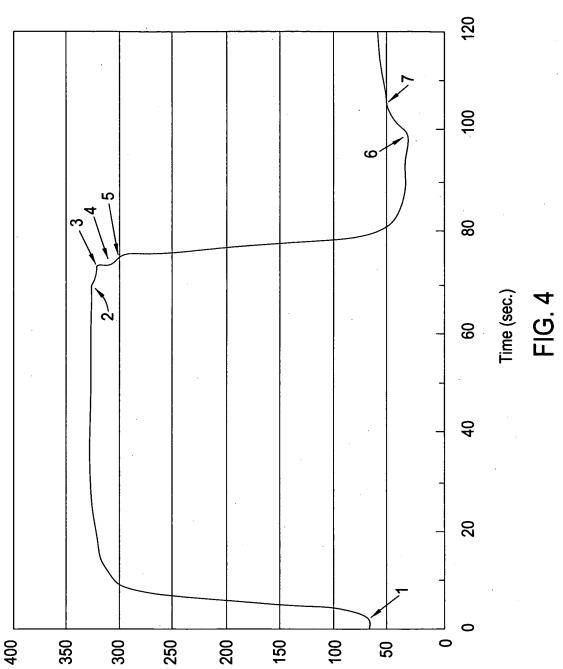
AMAT/1717.C3/CPES/DT/PJS
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Wafer Temperature at Center (C)



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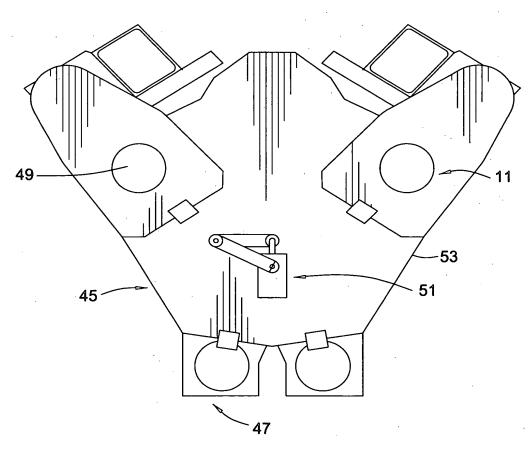


FIG. 5